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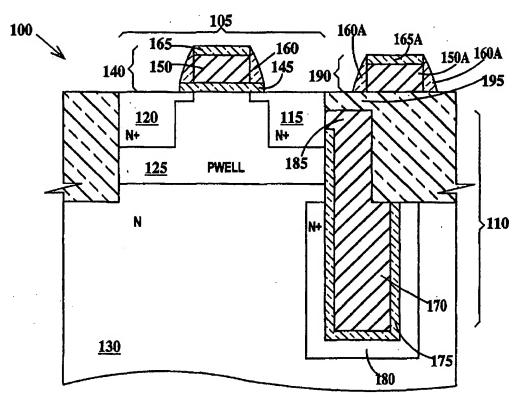
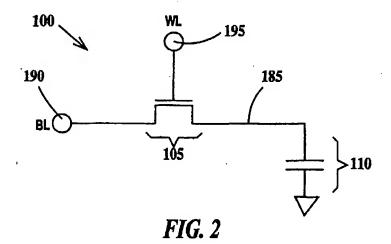
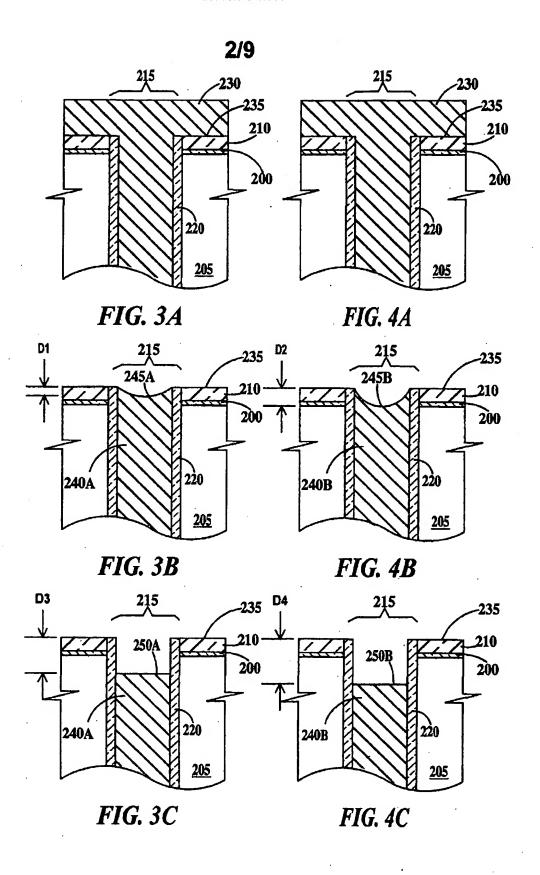
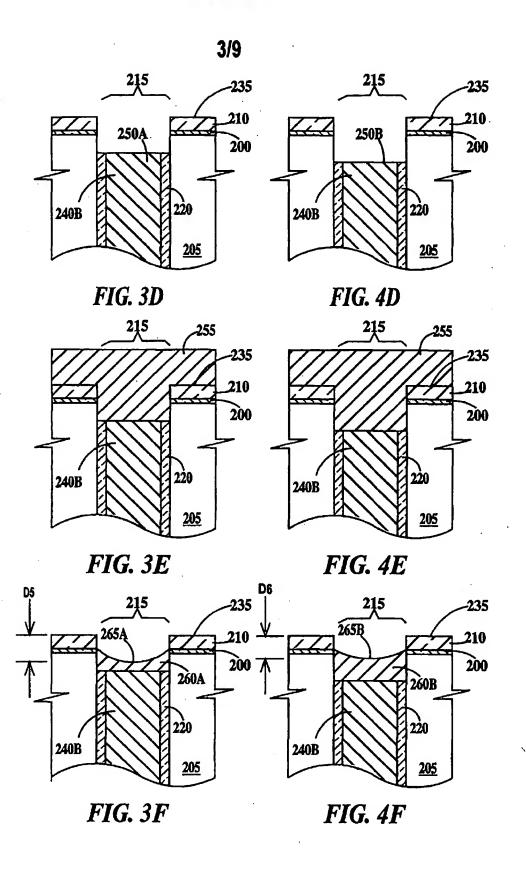
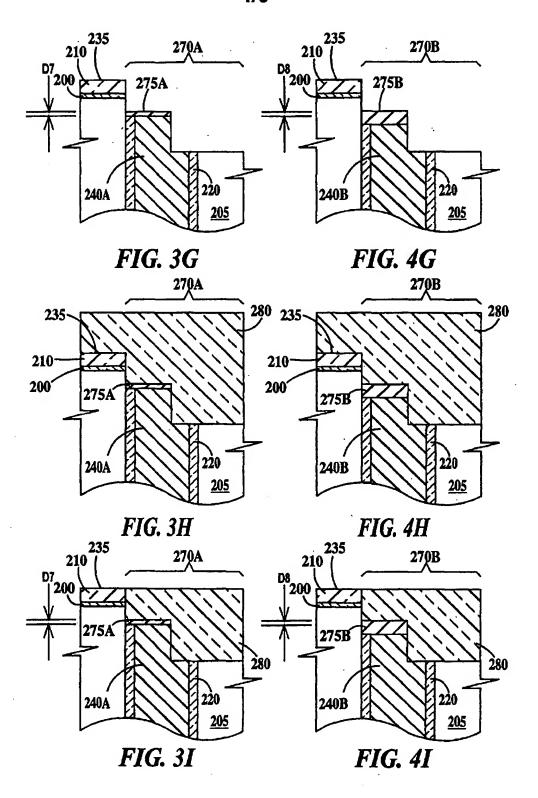


FIG. 1









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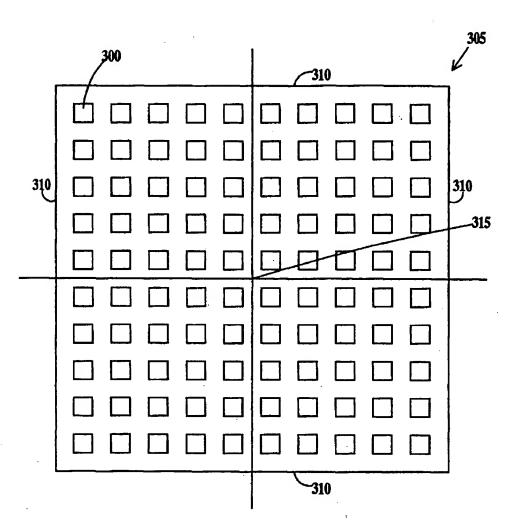
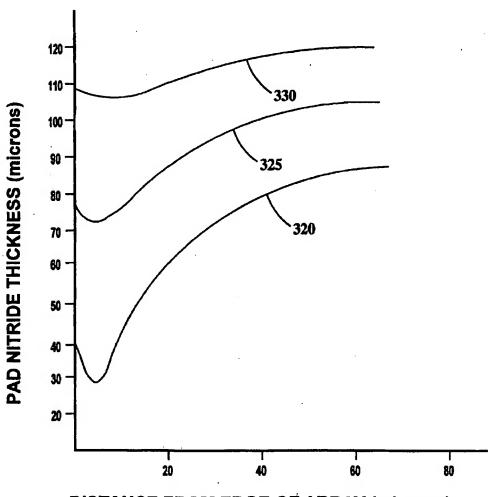


FIG. 5

PAD NITRIDE THICKNESS vs. DISTANCE FROM EDGE OF ARRAY



DISTANCE FROM EDGE OF ARRAY (microns)

FIG. 6

PAD NITRIDE THICKNESS vs. POLYSILICON RECESS DEPTH

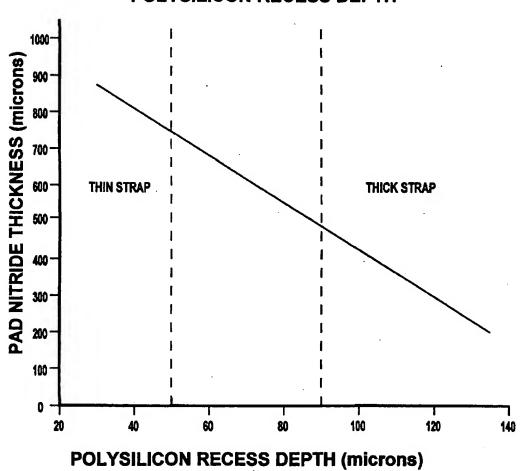


FIG. 7

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CMP TEMPERATURE vs. POLYSILICON DISHING

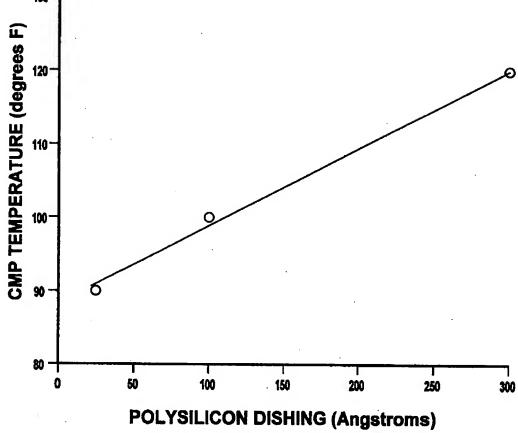


FIG. 8

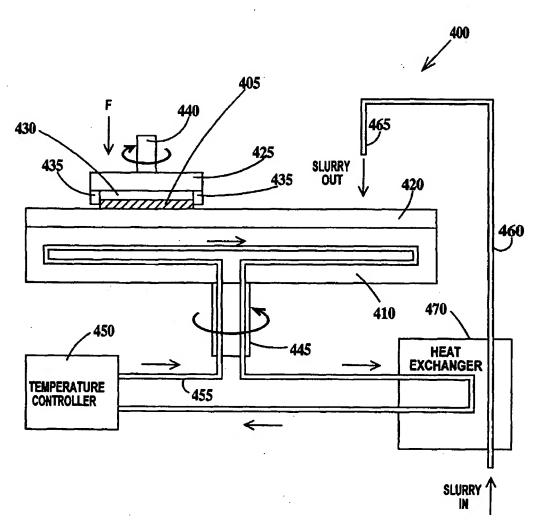


FIG. 9